SN54F74, SN74F74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

SDFS046A - MARCH 1987 - REVISED OCTOBER 1993

 Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

These devices contain two independent positive-edge-triggered D-type flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input may be changed without affecting the levels at the outputs.

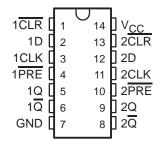
The SN54F74 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F74 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

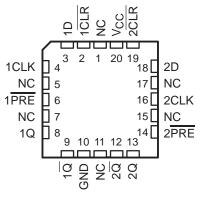
	INP	UTS		OUTI	PUTS
PRE	CLR	CLK	D	Q	Ø
L	Н	Х	Χ	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	H [†]	H [†]
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Χ	Q ₀	\overline{Q}_0

[†] The output levels are not guaranteed to meet the minimum levels for V_{OH}. Furthermore, this configuration is nonstable; that is, it will not persist when PRE or CLR returns to its inactive (high) level.

SN54F74...J PACKAGE SN74F74...D OR N PACKAGE (TOP VIEW)



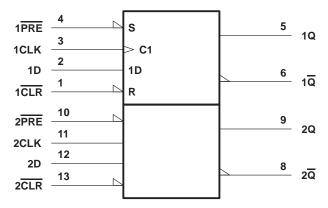
SN54F74 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

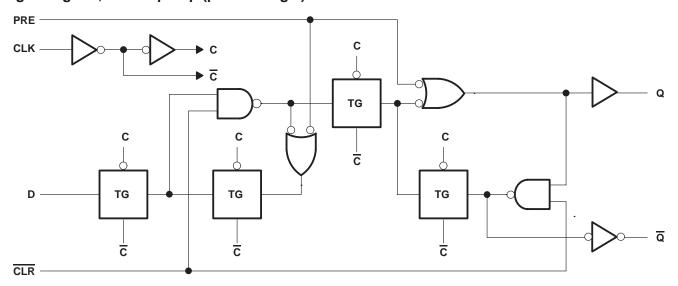
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	1.2 V to 7 V
Input current range	30 mA to 5 mA
Voltage range applied to any output in the high state	\dots -0.5 V to V _{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range: SN54F74	. −55°C to 125°C
SN74F74	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.



SN54F74, SN74F74 **DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS** WITH CLEAR AND PRESET

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recommended operating conditions

			SN54F74		9	N74F74		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
ΙK	Input clamp current			-18			-18	mA
IOH	High-level output current			-1			- 1	mA
lOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	ARAMETER	TEC	T CONDITIONS	,	SN54F74			N74F74		UNIT
PF	ARAWETER	153	TEST CONDITIONS			MAX	MIN	TYP	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V
V/01.1		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.5	3.4		V
VOH		$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA}$				2.7			٧
VOL		$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.3	0.5		0.3	0.5	V
Ц		$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
lіН		$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
1	Data, CLK	V _{CC} = 5.5 V,	V _I = 0.5 V			- 0.6			- 0.6	mA
IIL	PRE or CLR	v CC = 5.5 v,	V = 0.5 V			- 1.8			- 1.8	IIIA
los‡		$V_{CC} = 5.5 V,$	V _O = 0	-60		-150	-60		-150	mA
ICC		$V_{CC} = 5.5 \text{ V},$	See Note 2		10.5	16		10.5	16	mA

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} = 5 V, T _A = 25°C		SN54F74		SN74F74		UNIT	
			MIN MAX		MIN	MAX	MIN	MAX		
f _{clock}	Clock frequency		0	100	0	80	0	100	MHz	
	Pulse duration	CLK high, PRE or CLR low	4		4		4		20	
t _W	ruise duration	CLK low	5		6		5		ns	
	Saturations data hatara CLIVA	High	2		3		2			
t _{su}	Setup time, data before CLK↑	Low	3		4		3		ns	
	Setup time, inactive-state before CLK↑§	PRE or CLR to CLK	2		3		2			
. .	Hold time, data after CLK↑	High	1		2		1		no	
t _h	Holu tille, uata alter CLN	Low	1		2		1		ns	

[§] Inactive-state setup time is also referred to as recovery time.



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: ICC is measured with D, CLK, and PRE grounded then with D, CLK, and CLR grounded.

SN54F74, SN74F74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET SDFS046A – MARCH 1987 – REVISED OCTOBER 1993

switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = 25^{\circ}\text{C}$			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω, T_A = MIN to MAX† SN54F74 SN74F74				UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			100	145		80		100		MHz
tPLH	CLK	Q or \overline{Q}	3	4.9	6.8	3.8	8.5	3	7.8	ns
t _{PHL}	CLK		3.6	5.8	8	4.4	10.5	3.6	9.2	115
t _{PLH}	PRE or CLR	Q or $\overline{\mathbb{Q}}$	2.4	4.2	6.1	3.2	8	2.4	7.1	nc
t _{PHL}	FRE OF CLR		2.7	6.6	9	3.5	11.5	2.7	10.5	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 3: Load circuits and waveforms are shown in Section 1.



25-Jan-2012

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9759201Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9759201QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
5962-9759201QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
JM38510/34101B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/34101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/34101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/34101B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/34101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/34101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SN54F74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74F74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74F74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74F74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74F74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F74NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54F74FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	

PACKAGE OPTION ADDENDUM

25-Jan-2012

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54F74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54F74W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

www.ti.com

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54F74, SN74F74:

Catalog: SN74F74

Military: SN54F74

NOTE: Qualified Version Definitions:



25-Jan-2012

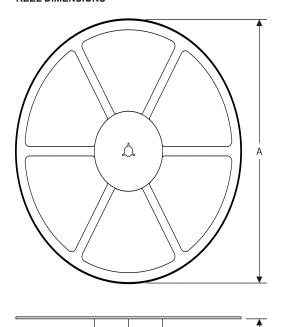
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

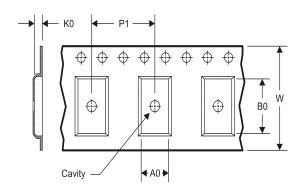
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F74DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74F74NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F74DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74F74NSR	SO	NS	14	2000	367.0	367.0	38.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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